IN THE CLAIMS

1. (original) A method of fabricating solder assemblies comprising the steps of:

(a) providing a component including a dielectric base having a non solder-wettable surface, a plurality of pads exposed to said surface and an electrically conductive potential plane element having a non solder-wettable surface, the potential plane element overlying said surface of said base, said potential plane element having openings therein, said pads being exposed through said openings;

(b) providing a mass of molten solder on each such pad so that the molten solder on each such pads wets the pad; and

(c) cooling the solder and pads to solidify the solder and thereby provide solder masses on said pads projecting through said openings in said potential plane element, (at least some of said solder masses being electrically isolated from said potential plane element.)

2. (original) A method as claimed in claim 1 wherein at least some of said masses of molten solder contact the potential plane element while in the molten state but retract away from the potential plane element before said solidification step under the influence of surface tension of the molten solder.

3. (original) A method as claimed in claim 1 wherein said potential plane element has at least one solder-wettable region, said step of providing said masses of molten solder including the step of providing a mass of molten solder in contact with at least one said solder-wettable region.

4. (currently amended) A method as claimed in claim 1 wherein said at least one solder-wettable region includes a solder-wettable region adjacent one or more pads of said

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component and wherein said step of providing masses of molten solder includes the step of providing a mass in contact with a pad and with a solder-wettable region of said potential plane so that after said cooling step such mass will form a solder connection between such pad and said potential plane.

    5.   (withdrawn)

    6.   (withdrawn)

    7.   (withdrawn)

    8.   (withdrawn)

    9.   (withdrawn)

    10.   (withdrawn)